

## 60V N-Channel Enhancement Mode Power MOSFET

### General Description

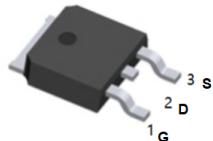
The STD35NF06 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### Features

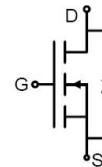
- $V_{DS} = 60V, I_D = 35A$
- $R_{DS(ON)}, 20m\Omega$  (Typ) @  $V_{GS} = 10V$
- $R_{DS(ON)}, 16m\Omega$  (Typ) @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

### Application

- Load Switch
- PWM Application
- Power management



TO-252(DPAK) top view



Schematic Diagram

### Absolute Maximum Ratings( $TA=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	60	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current-Continuous <sup>Note3</sup>	TC=25°C		35	A
	TC=100°C		25	A
Drain Current-Pulsed <sup>Note1</sup>		$I_{DM}$	140	A
Avalanche Energy <sup>Note4</sup>		$E_{AS}$	72	mJ
Maximum Power Dissipation	TC=25°C	$P_D$	105	W
Storage Temperature Range		$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range		$T_J$	-55 to +150	°C

### Thermal Resistance

Parameter	Symbol	Min.	Typ.	Max	Unit
Thermal Resistance,Junction-to-Case	$R_{\theta JC}$	-	-	1.4	°C/W

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### **Electrical Characteristics(TJ=25°C unless otherwise noted)**

<b>OFF CHARACTERISTICS</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_{DS}=250\mu A$	60	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1.0	$\mu A$
Gate-Body Leakage	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA

<b>ON CHARACTERISTICS</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	2	3	4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_{DS}=30A$	-	12	20	$m\Omega$
		$V_{GS}=4.5V, I_{DS}=20A$	-	16		$m\Omega$

<b>DYNAMIC CHARACTERISTICS</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
Input Capacitance	$C_{iss}$	$V_{DS} = 25V, V_{GS} = 0V,$ $f=1MHz$	-	1300	-	pF
Output Capacitance	$C_{oss}$		-	300	-	
Reverse Transfer Capacitance	$C_{rss}$		-	105	-	

<b>SWITCHING CHARACTERISTICS</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
Turn-On Delay Time	$T_{d(on)}$	$V_{GS}=10V, V_{DS}=30V,$ $R_{GEN}=4.7\Omega$ $I_D=27.5A$	-	20	-	ns
Rise Time	$t_r$		-	50	-	
Turn-Off Delay Time	$T_{d(off)}$		-	36	-	
Fall Time	$t_f$		-	15	-	
Total Gate Charge at 10V	$Q_g$	$V_{DS}=30V, I_{DS}=55A,$ $V_{GS}=10V$	-	44.5	60	nC
Gate to Source Gate Charge	$Q_{gs}$		-	10.5	-	
Gate to Drain "Miller" Charge	$Q_{gd}$		-	17.5	-	

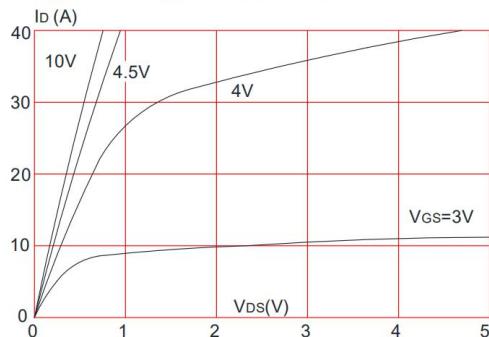
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
<b>Parameter</b>	<b>Symbol</b>	<b>Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{DS}=35A$	-	-	1.5	V
Reverse Recovery Time	$t_{rr}$		-	75	-	$\mu S$
Reverse Recovery Charge	$Q_{rr}$	$di/dt=100A/\mu s$	-	170	-	$\mu C$

### **Notes:**

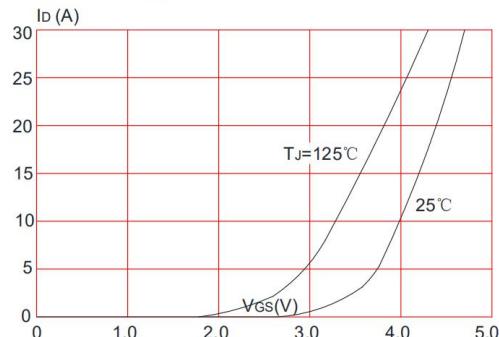
- 1: Repetitive rating, pulse width limited by maximum junction temperature.
- 2: Surface mounted on FR4 Board,  $t \leq 10sec$ .
- 3: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4: EAS condition:  $L=0.5mH, VDD=10V, VG=10V, V_{GATE}=20V, Start\ TJ=25^\circ C$ .

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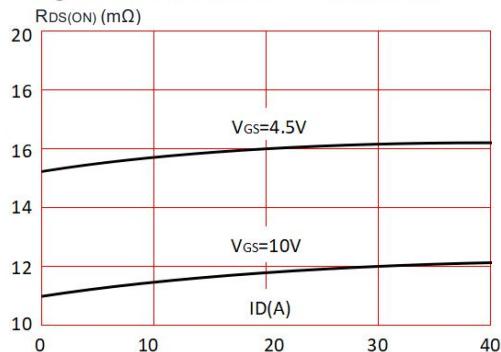
**Figure 1:** Output Characteristics



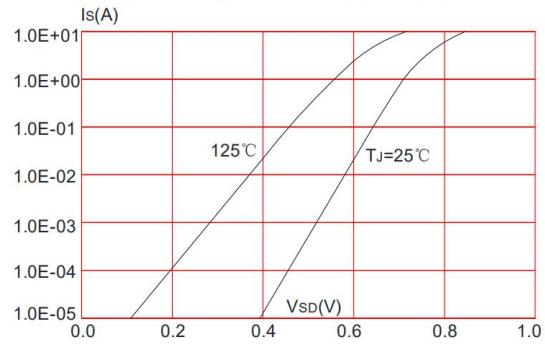
**Figure 2:** Typical Transfer Characteristics



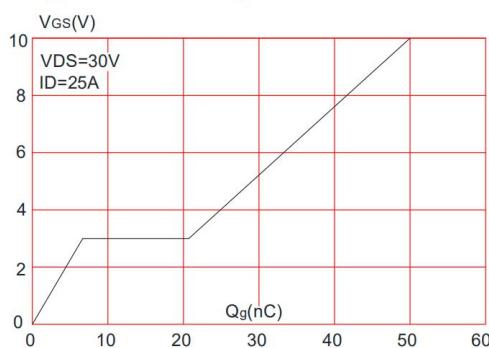
**Figure 3:** On-resistance vs. Drain Current



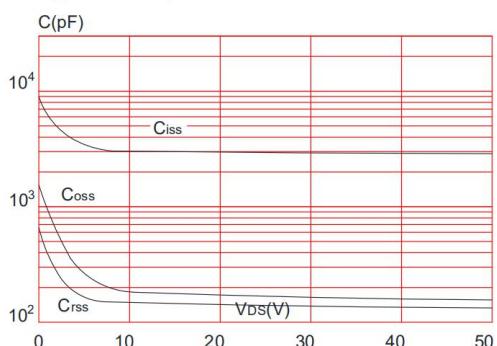
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

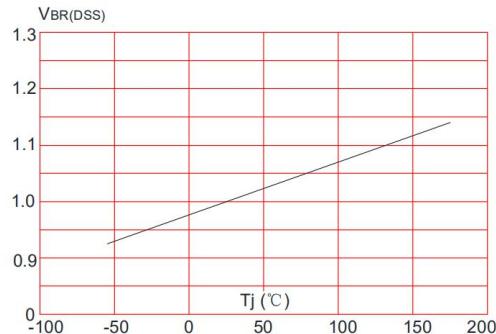


**Figure 6:** Capacitance Characteristics

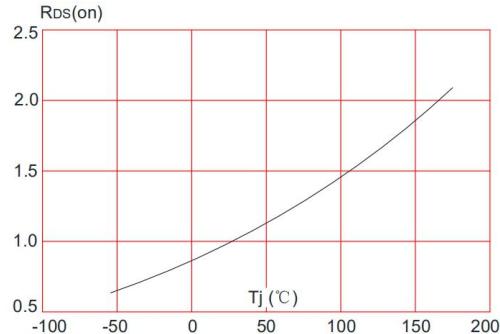


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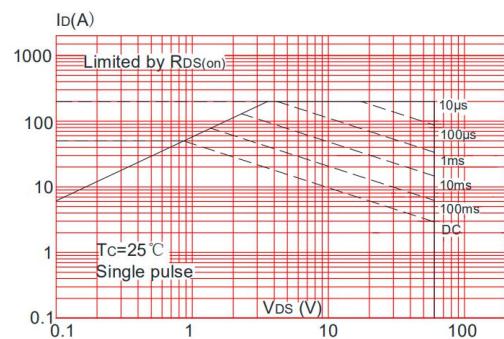
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



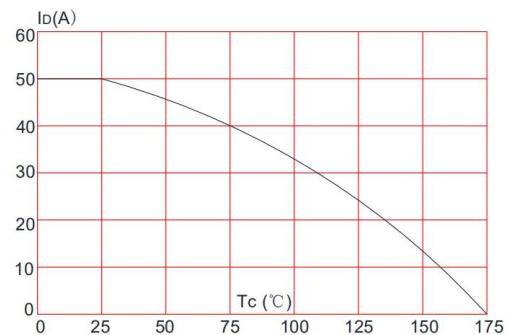
**Figure 8:** Normalized on Resistance vs. Junction Temperature



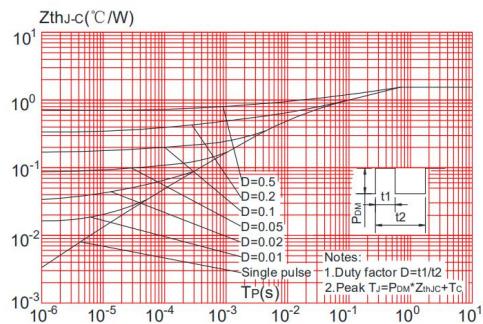
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



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### Test Circuit

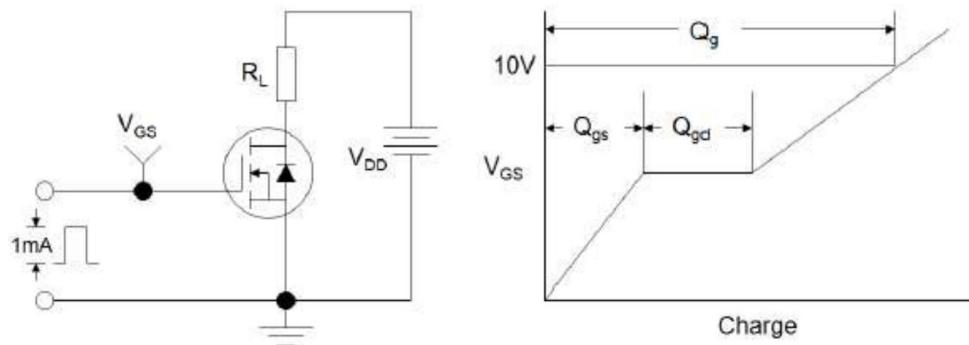


Figure1:Gate Charge Test Circuit & Waveform

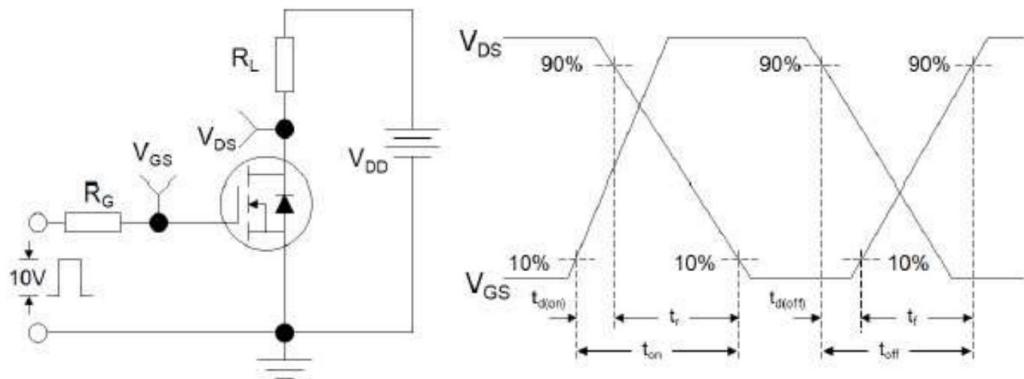


Figure 2: Resistive Switching Test Circuit & Waveforms

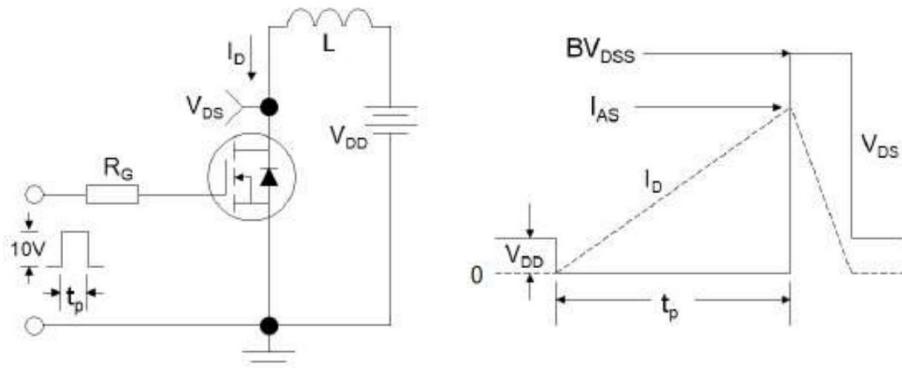
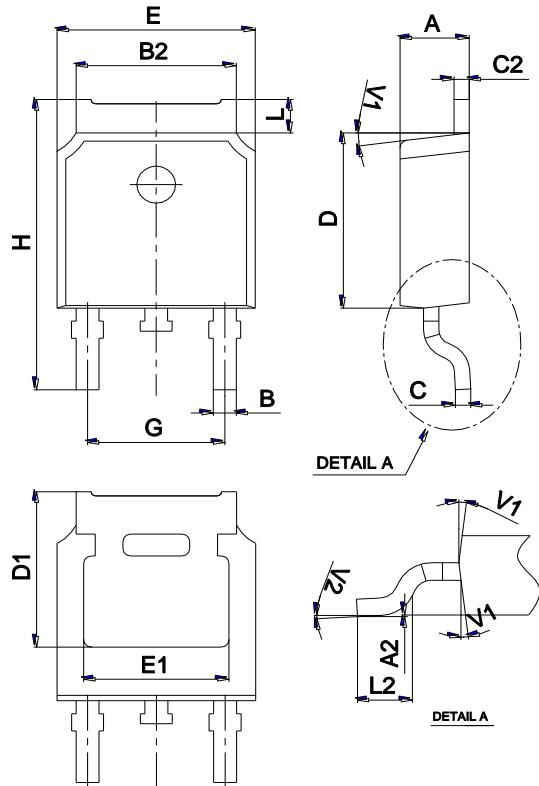


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

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**Package Mechanical Data TO-252**



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

**Ordering information**

Order code	Package	Baseqty	Delivery mode
STD35NF06L	TO-252	2500	Tape and reel